

N-Channel ENHANCEMENT MODE POWER MOSFET

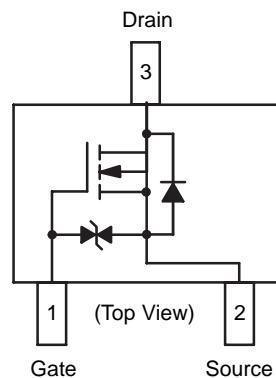
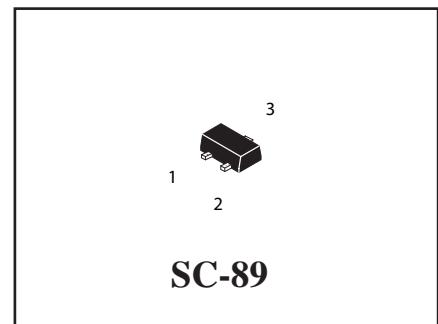
 **Pb** Lead(Pb)-Free

FEATURES:

- * Gate-Source ESD Protected: 1500 V
- * Fast Switching Speed
- * Low On-Resistance
- * Low Voltage Driver

APPLICATIONS:

- * Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- * Battery Operated Systems
- * Power Supply Converter Circuits
- * Load/Power Switching Cell Phones, Pagers



Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Characteristic	Symbol	Values	Unit
Drain-Source Voltage	V_{DSS}	60	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current	I_D	115	mA
	I_{DP}^1	800	mA
Reverse drain current	I_D	115	mA
	I_{DRP}^1	800	mA
Total Power Dissipation	P_D^2	225	mW
Junction temperature Range	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$

Note 1. $P_w \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

2. When mounted on a $1 \times 0.75 \times 0.062$ inch glass epoxy board

Device Marking

2N7002KT = RS

Electrical Characteristics (T_A=25°C unless otherwise specified, per element)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS (Note2)					
Drain-Source Breakdown Voltage V _{GS} =0V, I _D =10μA	V _{(BR)DSS}	60	-	-	V
Zero Gate Voltage Drain Current V _{DS} =60V, V _{GS} =0V	I _{DSS}	-	-	1.0	μA
Gate-source Leakage V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±10	μA

ON CHARACTERISTICS (Note2)

Gate Threshold Voltage V _{DS} =V _{GS} , I _D =250μA	V _{GS(th)}	1.0	1.5	2.0	V
Static Drain-Source On-Resistance V _{GS} =10V, I _D =0.5A V _{GS} =5V, I _D =0.05A	R _{D(S)ON}	-	-	7.5 7.5	Ω
Forward transfer admittance V _{DS} =10V, I _D =0.2A	g _{fs} *	80	-	-	mS

DYNAMIC CHARACTERISTICS

Input Capacitance V _{DS} =25V, V _{GS} =0V, f=1.0MHz	C _{iss}	-	25	50	pF
Output Capacitance V _{DS} =25V, V _{GS} =0V, f=1.0MHz	C _{oss}	-	10	25	
Reverse Transfer Capacitance V _{DS} =25V, V _{GS} =0V, f=1.0MHz	C _{rss}	-	3.0	5.0	

SWITCHING CHARACTERISTICS

Turn-On Delay Time I _D =0.2A, V _{DD} =30V V _{GS} =10V, R _L =150Ω, R _G =10Ω	T _{D(ON)*}	-	12	20	nS
Turn-Off Delay Time I _D =0.2A, V _{DD} =30V V _{GS} =10V, R _L =150Ω, R _G =10Ω	T _{D(OFF)*}	-	20	30	

*Pw ≤ 300μs, Duty cycle ≤ 1%

Characteristics Curve

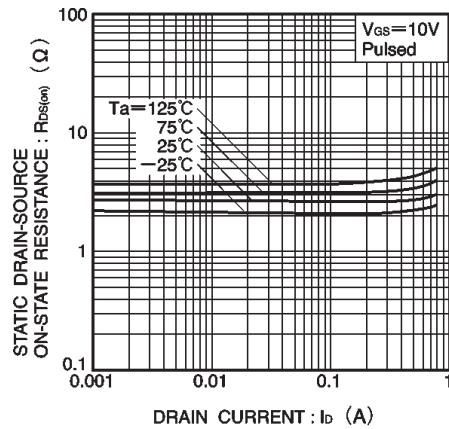


Fig.4 Static drain-source on-state resistance vs. drain current (I)

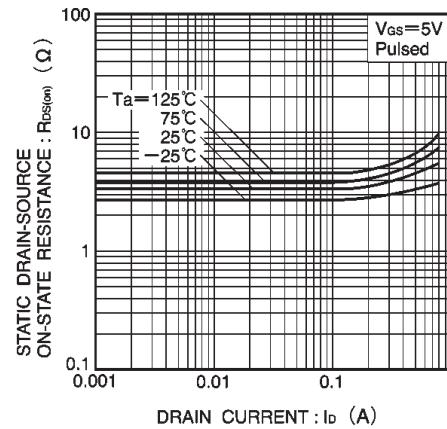


Fig.5 Static drain-source on-state resistance vs. drain current (II)

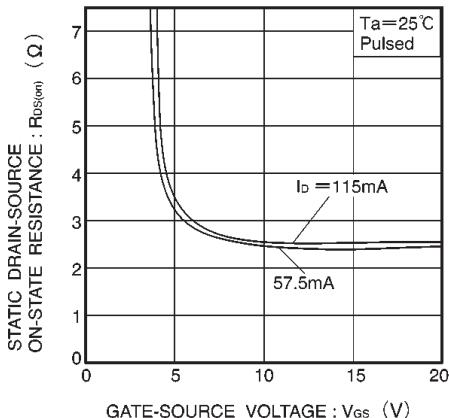


Fig.6 Static drain-source on-state resistance vs. gate-source voltage

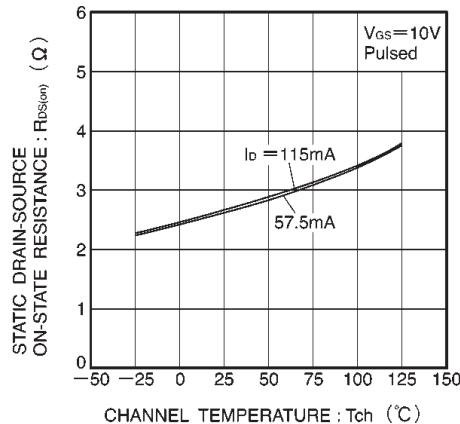


Fig.7 Static drain-source on-state resistance vs. channel temperature

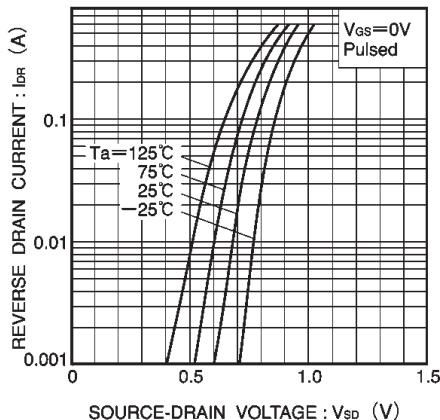


Fig.8 Reverse drain current vs. source-drain voltage (I)

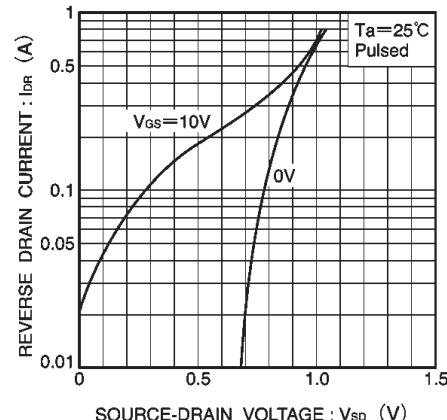


Fig.9 Reverse drain current vs. source-drain voltage (II)

Characteristics Curve

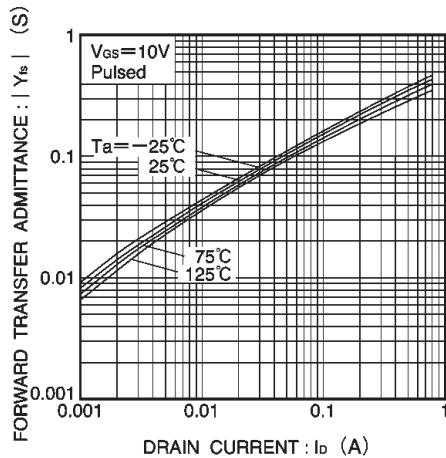


Fig.10 Forward transfer admittance
vs. drain current

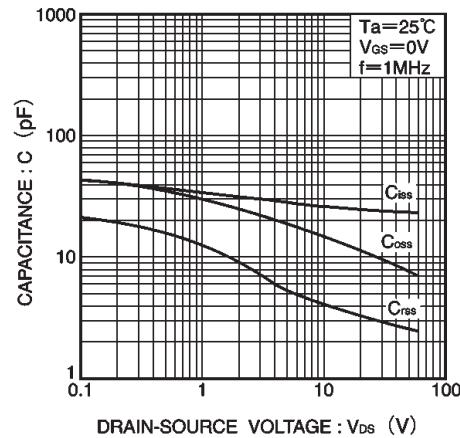


Fig.11 Typical capacitance
vs. drain-source voltage

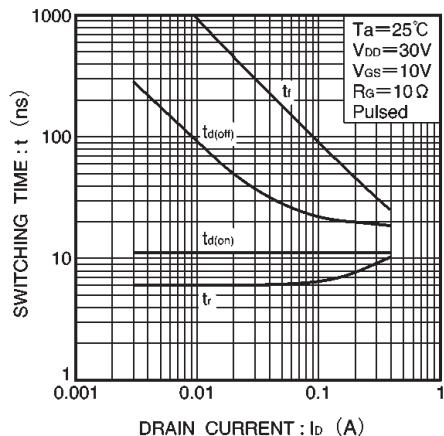
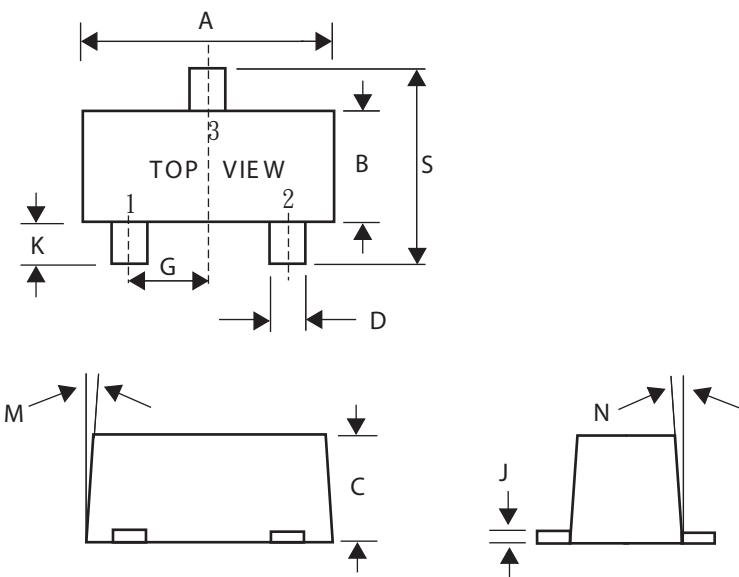


Fig.12 Switching characteristics
(See Figures 13 and 14 for the
measurement circuit and resultant waveforms)

SC-89 Outline Demensions

Unit:mm



SC-89			
Dim	Min	Nom	Max
A	1.50	1.60	1.70
B	0.75	0.85	0.95
C	0.60	0.70	0.80
D	0.23	0.28	0.33
G	0.50BSC		
J	0.10	0.15	0.20
K	0.30	0.40	0.50
M	---	---	10°
N	---	---	10°
S	1.50	1.60	1.70